§ 04 — OVERVIEW

AT A GLANCE

One engineering platform. Nine product lines. **INTEGRATED, CALIBRATED, AND SUPPORTED ACROSS EUROPE** under defense-grade procurement controls.

01 **RESOLUTION**
Down to 5 µm voxel

02 **INSPECTION VOLUME**
Up to Ø 800 mm ×1000 mm height

03 **X-RAY SOURCES**
160 kV – 450 kV microfocus

04 **PRODUCT LINES**
Standard · Planar · X-Ray · Robot

05 **SHIELDING**
<1µSv/h +Live Monitoring

06 **INFORMATION CONTROL**
TISAX-compliant

// DELIVERED WITH

SITE SURVEY · CALIBRATION · ACCEPTANCE TEST · TRAINING

REQUEST
TECHNICAL BRIEF

SCAN OR EMAIL TO CONTACT

LAZPIUR

// ARRAY ICT — DEFENSE & AEROSPACE

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TISAX-COMPLIANT PROCESSES

MACHINERY AND ELECTROMAGNETIC COMPATIBILITY
2006 / 42 / EC
2014 / 30 / EU
IEC/CN 61010-2-091
CFR 1020.40

QUALITY MANAGEMENT
ISO 9001:2015
VDA 6, PARTS 4, 3. 2017 EDITION

OCCUPATIONAL HEALTH AND SAFETY MANAGEMENT
BS OHSAS 18001:2007

LABORATORY ACCREDITATION AND TESTING
ISO/IEC 17025:2005

RESILIENCE FOR EUROPE

LAZPIUR

SEE INSIDE WHAT MATTERS.

Industrial Computed Tomography Solutions — Integrated, and supported across Europe.

// CLASSIFIED-READY

§ 01 — TECHNOLOGY

CRITICAL INSPECTION

SURFACE INSPECTION ENDS HERE.

Visual and ultrasonic methods qualify external geometry. Industrial iCT is the only modality that **maps the internal volume** of a component — voxel by voxel — at the resolution defense programs demand.

WHAT iCT SEES

01 **POROSITY**
Lack-of-fusion voids and trapped powder in AM.

02 **DELAMINATION**
Interlaminar separation in ceramic-composite armor.

03 **BRAZE VOIDS**
Bond integrity in missile and turbine assemblies.

04 **PROPELLANT CRACKS**
Grain fissures and case-bond defects in solid motors.

05 **COUNTERFEIT DIE**
Repackaged or substituted components in electronics.

06 **INTERNAL STRUCTURE**
Components manufactured to exact tolerances.

§ 02 — INDUSTRIES

APPLICATIONS

MUNITIONS

Verify shell-body integrity, propellant fill density, and seal continuity without destructive teardown.

ARMOR

Characterize delamination, fiber alignment, and ballistic damage across layered ceramic-composite armor systems.

AM COMPONENTS

Quantify porosity, inclusions, and lattice defects in additively manufactured flight-critical metal hardware.

INTEGRITY

Inspect grain structure, bond-line continuity, and casting voids in solid rocket motor sections.

ELECTRONICS

Detect counterfeit components, solder voids, and wire-bond failures in mission-critical electronic boards.

FORENSICS

Reverse-engineer legacy hardware and isolate failure modes during depot-level overhaul and recertification.

§ 03 — PRODUCT

SYSTEM RANGE

CT-STD · 01

STANDARD LINE

Off-line laboratory iCT for qualification, R&D, and forensic teardown.

SOURCE	VOXEL	MODE
From 160 - 450kV	6 µm	Cabinet

CT-PLN · 02

PLANAR LINE

High-resolution X-ray for semiconductor packages, PCBs, and electronic assemblies.

SOURCE	SAMPLE	RESOLUTION	MODE
160 kV	Flat / thin	10 µm	2D

IL-XR · 03

IN-LINE X-RAY

High-cadence 2D radiography for real-time inspection on the production line.

SOURCE	CYCLE	MODE
From 160 - 225 kV	< 5 s/part	2D · Live

CT-ROB · 04

ROBOT LINE

In-line iCT integrated with two 6-axis robotic handling for serial production verification.

SOURCE	CYCLE	MODE
From 160 - 450kV	Custom	In-line